

WAFER HANDLING ROBOT

H-ZERO (H0)

Innovative, high-performance, all-in-one design eliminates external controller and interconnecting cables

Modular, compact body with **minimal footprint** allows for easy tabletop mounting

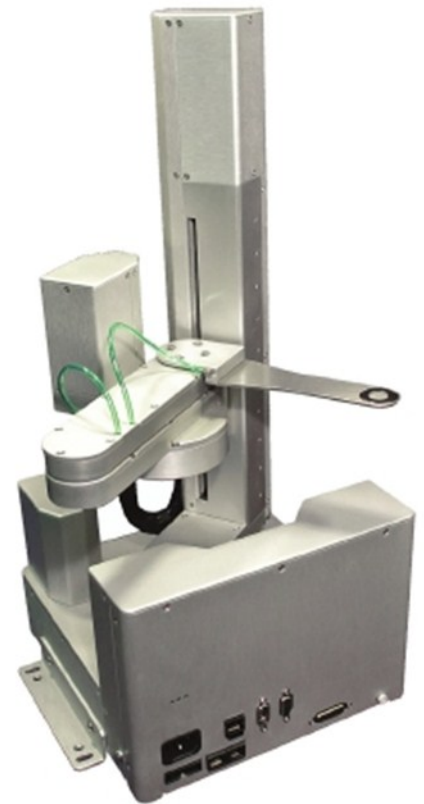
Advanced real-time motion control kernel delivers accurate motion profiling along smooth continuous trajectories for radial and in-line stations

High customizability, comprehensive set of software utilities, and powerful native wafer handling language facilitate **rapid integration into OEM application environments**

Distributed control architecture allows for seamless integration with linear tracks, prealigners, and other peripheral components

Driven by ultra low inertia brushless motors for **smooth, instant response**

Class 1 clean-room compatible

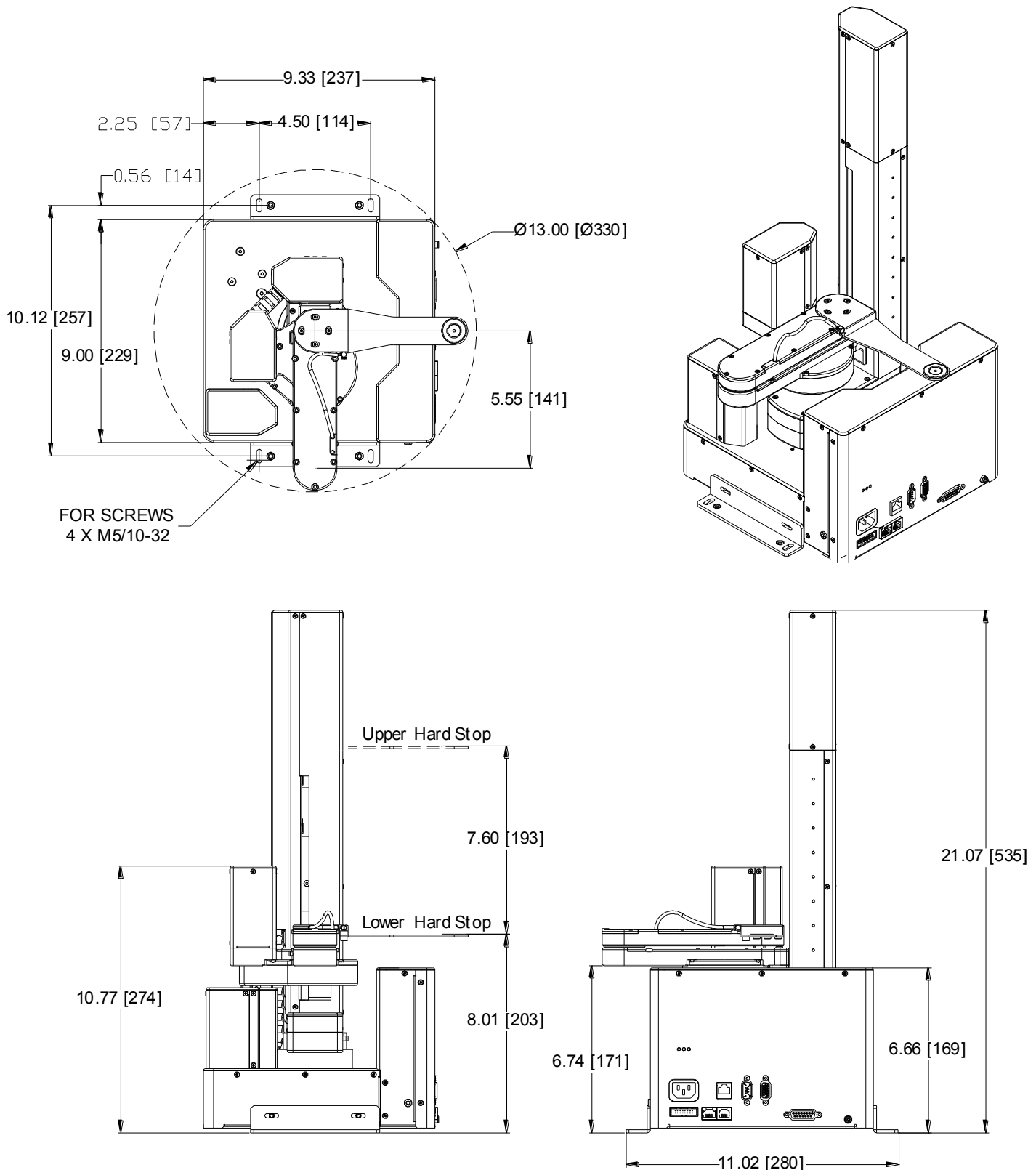


H-ZERO SPECIFICATIONS

Axis	Range of Motion	Maximum Velocity	Maximum Acceleration	Axis Repeatability
T	365° between hard stops	300°/s	1500°/s ²	±0.01°
R	11.10 in. fully extended arm	30 inch/s	300 inch/s ²	±0.001 in. (0.025mm)
Z	7.6 in. between hard stops	10 inch/s	30 inch/s ²	±0.001 in. (0.025mm)

Wafer Diameter	Up to 8 in. (200 mm)
Payload	0.45 lbs. (0.200 kg)
Encoders	Incremental, 10000 pulse/motor shaft revolution
Motor Type	Ultra low-inertia, brushless
Weight	17.5 lbs. (8 kg)
Operating temperature	50°F to 104°F (10°C to 40°C)
Facility Requirements	Power: Line Voltage 100VAC to 240VAC Vacuum Supply: 11.8 in Hg (-5.8 psi)/0.1 CFM airflow
MTBF	> 60000 hours
MCBF	> 10,000,000 cycles

H-ZERO GENERAL DIMENSIONS



NOTE: All dimensins - inch[mm]